

PARTNER QUOTE SHEET

Snapdragon X75, X72, and X35 5G M.2 and LGA Reference Designs



Askey

"Snapdragon X75 and X72 with leading-edge 5G NR and Wi-Fi 7 technologies are the latest advanced 5G chips. Askey's world-class 5G FWA powered by Snapdragon X75 and X72 will deliver a new experience of high-speed and low-latency data service," said Robert Lin, Chief Executive Officer, Askey. "With Qualcomm Technologies' support, we will continue to provide more valuable 5G FWA products to market."

Compal

"Compal and Qualcomm Technologies have a longstanding history of bringing new technology and innovation into commercial products," said Yiyun Chang, Vice President, Compal Electronics. "We're delighted to see Qualcomm Technologies introduce Snapdragon X75, X72, and X35 5G Reference Designs, and enable more Compal 5G Module solutions to support customers with enhanced 5G connectivity and use cases in consumer and vertical markets."

Foxconn

"We are excited to once again partner with Qualcomm Technologies to bring products based on their latest 3GPP Release 17 5G solutions, including Snapdragon X72, X75, and X35, to market. As a global leading smart manufacturer, we are proud to collaborate with our long-term partner to provide innovative products that bring people more convenience, creativity, and joy," said Kevin Liu, Vice President, Foxconn Industrial Internet. "We look forward to continuing our successful collaboration with Qualcomm Technologies and delivering groundbreaking 5G solutions that will help to shape the future in communication technology."

MeiG Smart

"As the first RedCap product, Snapdragon X35 meets customers' needs for low cost and low power consumption. In the future, MeiG will make deep use of Snapdragon X35 to develop more cost-effective and high-quality products, improve the performance of key indicators, and deepen the application scenarios," said Benjamin Du, Chief Executive Officer, MeiG Smart.

Quectel

"We are excited to roll out the industry's most advanced 5G NR modules based on Qualcomm Technologies' cutting-edge Snapdragon X75, X72, and X35," said Norbert Muhrer, President and Chief Sales Officer, Quectel Wireless Solutions. "Our latest generation 5G NR Release 17 modules, with engineering samples available for global markets in the first half of 2023, feature unprecedented powerful performance and leading advantages in data rates, capacity, power saving, and ultra-reliability. I believe they will provide an excellent Sub-6GHz, mmWave, and Wi-Fi 7 solution for the growing 5G eMBB and FWA market."

Sunsea AIoT

"We're glad to be the first batch of co-operators of Qualcomm Technologies adopting the new Snapdragon X35. Snapdragon X35 is the new-generation platform for 5G applications, which supports 5G RedCap, bringing down both power consumption, cost, and size of 5G modules," said Tao Yang, Chief Executive Officer, Sunsea AIoT. "Sunsea AIoT will launch new products based on Snapdragon X35 in the first half of 2023 to help our customers win not only in CPE, MIFI, Industrial CPE industry, but also laptop & PC and other areas. Having close cooperation with Qualcomm Technologies, Sunsea AIoT delivers 5G connectivity to IoT applications and customers with a high level of performance, stability, and flexibility, continuously driving the ongoing digital and smart transition in numerous vertical industries."

Telit

"Qualcomm Technologies is paving the way for faster 5G speeds and more reliable connections that our customers demand for their applications," said Marco Contento, Vice President, Product Management, Mobile Broadband, Telit Cinterion. "The Snapdragon X72 and X75 eMBB modem brings fiber-like connectivity to industrial routers, gateways, fixed wireless access, and customer-premise equipment that require higher broadband capacity and dependability for data storage and transmission. The Snapdragon X35 NR-Light modem is future ready for use cases that require 4G LTE speeds for use on 5G standalone networks. Ideal use cases for RedCap include automated guided vehicles, drones, electric power grids, factory automation, IP cameras, industrial robots, remote monitoring devices, and many more."

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Vantiva

"The certified module reference designs based on Snapdragon X75, X72, and X35 from Qualcomm Technologies is a significant development. It will help the industry greatly accelerate the maturity -- and facilitate the distribution -- of emerging 5G 3GPP Rel17-based solutions," said Ashwani Saigal, Vice President, Broadband and Video CPE, Vantiva. "All of Vantiva's 4G/5G CPE offerings are based on a modular architecture. It is the best model for scaling the production and deployment of Vantiva's fixed wireless access (FWA) solutions, making it possible for our teams to simultaneously deliver FWA CPE across regional markets while accommodating the specific 5G bandwidth profiles and frequency requirements of each operator."

WNC

"WNC are very excited about Qualcomm Technologies' rollout of Snapdragon X75 and X35. Their unwavering commitment to innovation in cellular technologies has enabled a plethora of life-enriching products and solutions," said CC Huang, BU Head, Connectivity and Embedded Module, WNC. "WNC has kicked off several important FWA (Fixed Wireless Access), Mobility, and IoT projects with strong support from Qualcomm Technologies. We look forward to 5G services and Qualcomm Technologies' solutions making an ever-far-reaching impact of many aspects of tomorrow's societies worldwide."